

B5817W-B5819W

Rev.F Mar.-2016

描述 / Descriptions

SOD-123 塑封封装 肖特基二极管。
Schottky Diode in a SOD-123 Plastic Package.

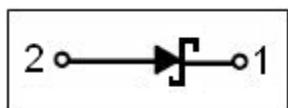
特征 / Features

低正向压降。
Low positive pressure drop.

用途 / Applications

肖特基二极管。
Schottky diode.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1:Cathode PIN2:Anode

放大及印章代码 / h_{FE} Classifications & Marking

Model	B5817W	B5818W	B5819W
Marking	HSJ	HSK	HSL

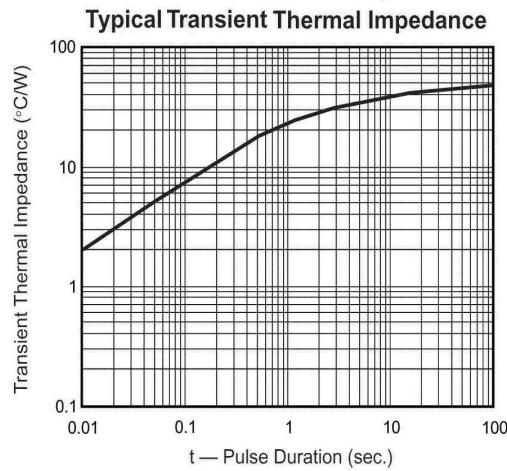
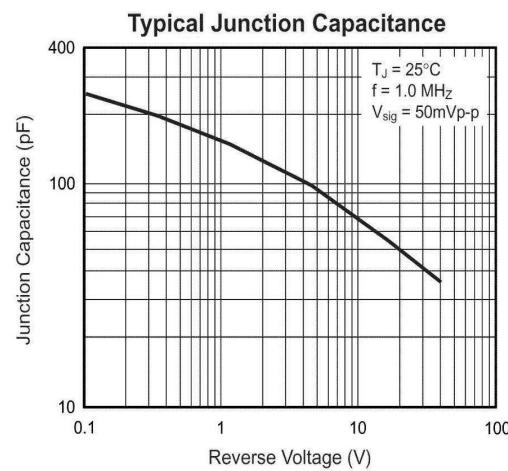
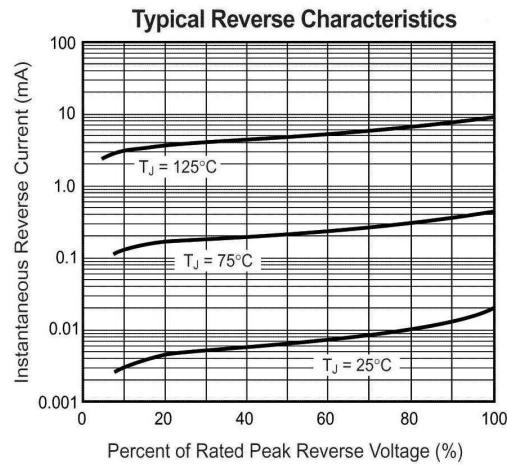
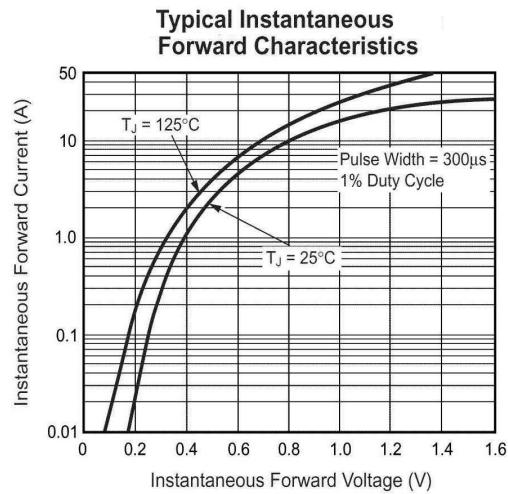
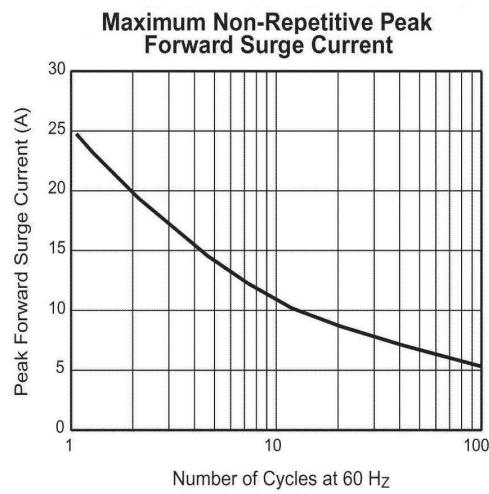
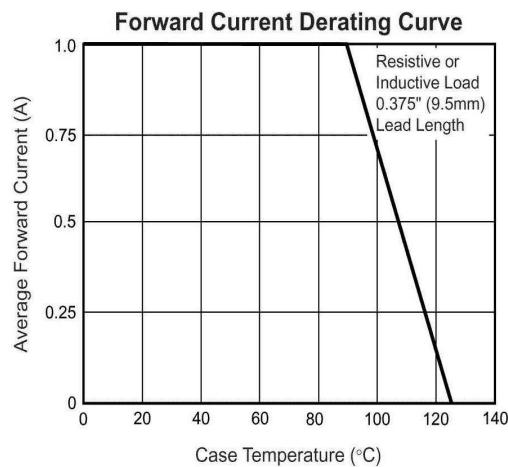
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating			单位 Unit
		B5817W	B5818W	B5819W	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Reverse Voltage	V_{RRM} V_{RWM} V_R	20	30	40	V
RMS Reverse Voltage	V_R (RMS)	14	21	28	V
Average Rectified Forward Current	I_F	1			A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	25			A
Power Dissipation	P_D	450			mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	220			°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	-65 to 125			°C

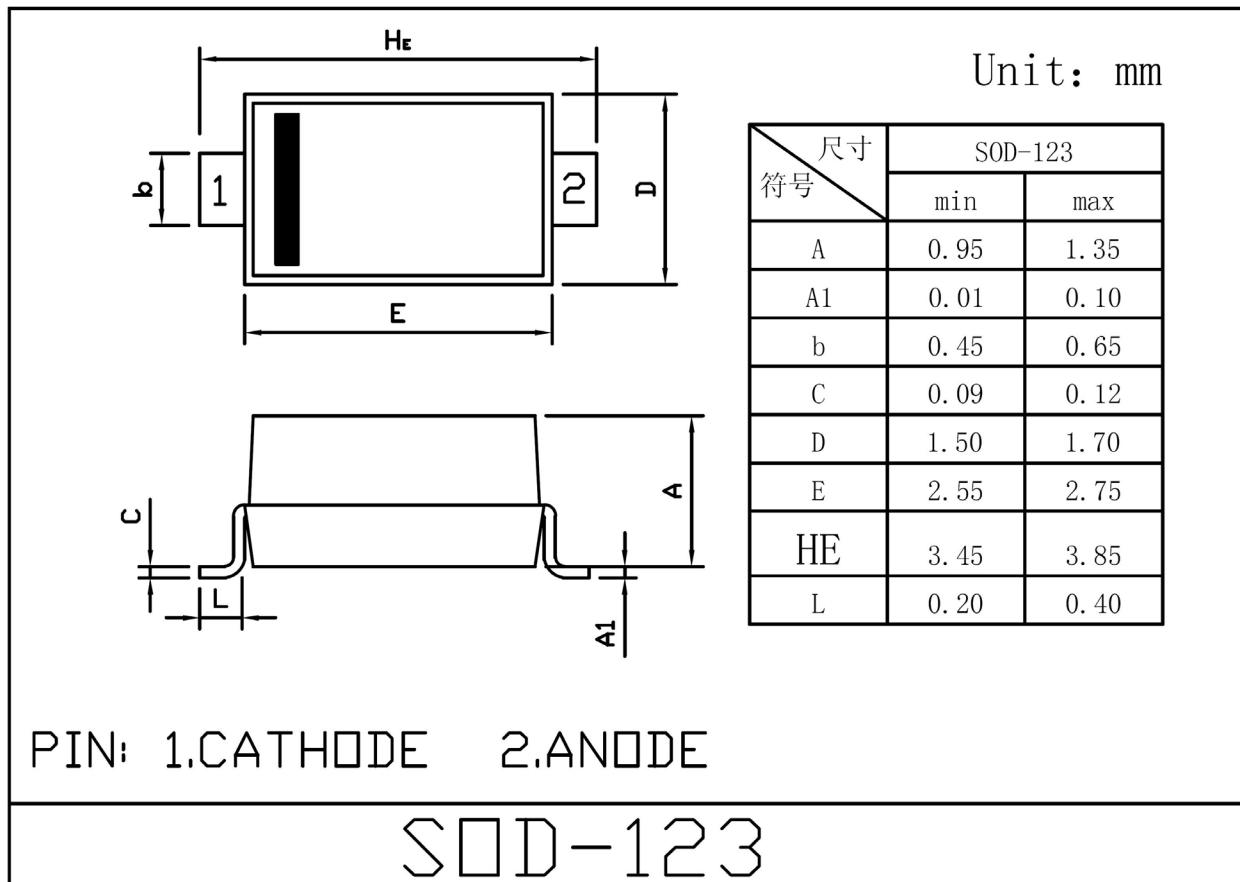
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating						单位 Unit	
			B5817W		B5818W		B5819W			
			MIN	MAX	MIN	MAX	MIN	MAX		
Reverse breakdown voltage	$V_{(BR)}$	$I_R=1mA$	20		30		40		V	
Forward Voltage	V_F	$I_F=0.1A$		0.32		0.35		0.40	V	
		$I_F=1A$		0.45		0.55		0.60		
		$I_F=3A$		0.75		0.80		0.90		
Instantaneous Reverse Current	I_{RM}	$V_R=V_{RRM}$	1						mA	
Junction Capacitance	C_J	$V_R=4V$ $f=1.0MHz$	120						pF	

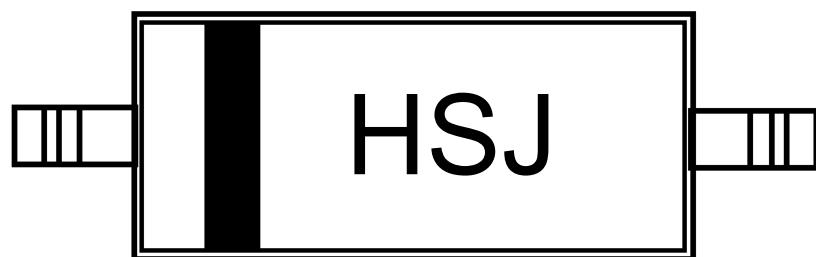
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

H : 为公司代码

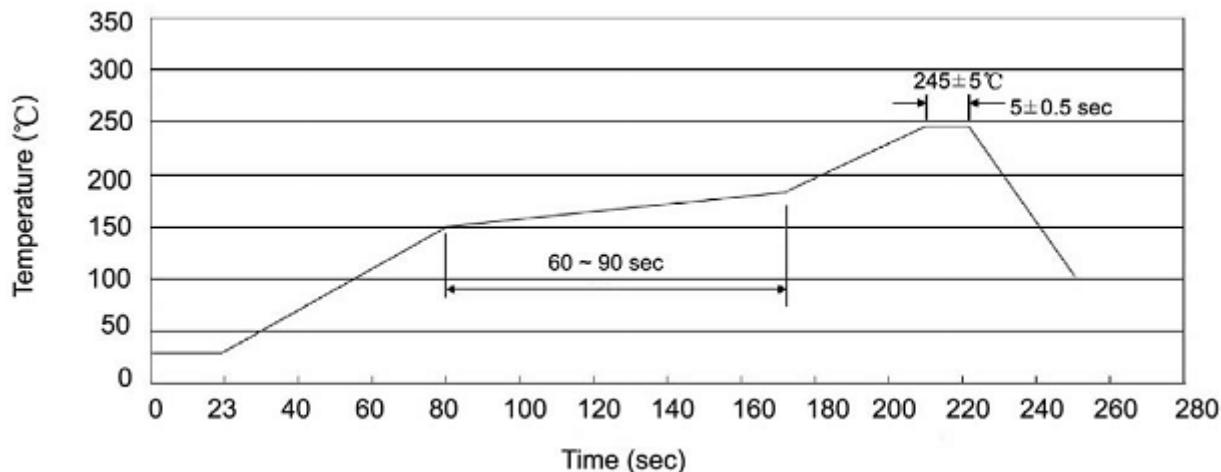
SJ : 为型号代码

Note:

H: Company Code.

SJ: Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 $25 \sim 150^\circ\text{C}$, 时间 $60 \sim 90\text{sec}$;
- 2、峰值温度 $245 \pm 5^\circ\text{C}$, 时间持续为 $5 \pm 0.5\text{sec}$;
- 3、焊接制程冷却速度为 $2 \sim 10^\circ\text{C/sec}$.

Note:

- 1.Preheating: $25\sim150^\circ\text{C}$, Time: $60\sim90\text{sec}$.
- 2.Peak Temp.: $245\pm5^\circ\text{C}$, Duration: $5\pm0.5\text{sec}$.
3. Cooling Speed: $2\sim10^\circ\text{C/sec}$.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度 : $260 \pm 5^\circ\text{C}$ 时间 : $10 \pm 1 \text{ sec.}$ Temp.: $260 \pm 5^\circ\text{C}$ Time: $10 \pm 1 \text{ sec}$

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123	3,000	10	30,000	8	240,000	7" ×8	180×120×180	385×257×392

使用说明 / Notices